Board Dhading

FABRICATION NOTES:

- 1. MATERIALS: ISOLA 370HR with 1/2 oz starting Copper and 1oz. copper plating.
- 2. Board is 8 layers, finished board thickness = .062'' + /- 10%. Shall conform to IPC-2221, UL 94V-0 and European Directive 2011/65/EC (ROHS2).
- 3. Finished board shall meet requirements of IPC-A-600. Finished trace width and outer diameter of plated holes shall be within .001" or less of image on photo tool master. Annular rings to meet IPC-600J class 2.
- 4. Holes to be plated through in accordance with IPC-600J. Dimensions shown are for finished plated through holes.
- 5. All exposed copper to be finished with ENIG, as per IPC-4552.
- 6. Screen legend with white non-conductive ink, both sides. Contact areas of SMT components to be free of ink.
- 7. SMOBC: BLACK LPI solder mask. Both sides.
- 8. Board to be 100% bare board tested and report provided.
- 9. Design rules used: 5mil trace, 5mil space.
- 10. Plated holes have a +/- 0.003 inch tolerance. Non-plated +/- 0.0015 unless otherwise specified
- 11. DO NOT adjust Stack-up or Trace widthes without contacting NEXTGEN RF.

DRILL TABLE

		I				
Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad
	307	8.00mil (0.203mm)	PTH	Round	Top Layer — Bottom Layer	Via
abla	1980	8.00mil (0.203mm)	PTH	Round	Top Layer — Bottom Layer	Via
Н	39	10.00mil (0.254mm)	PTH	Round	Top Layer — Bottom Layer	Via
∇	60	10.00mil (0.254mm)	PTH	Round	Top Layer — Bottom Layer	Pad
С	20	22.00mil (0.559mm)	PTH	Round	Top Layer — Bottom Layer	Pad
В	2	24.00mil (0.610mm)	PTH	Slot	Top Layer — Bottom Layer	Pad
0	2	25.59mil (0.650mm)	NPTH	Round	Top Layer — Bottom Layer	Pad
\bowtie	2	27.56mil (0.700mm)	PTH	Slot	Top Layer — Bottom Layer	Pad
❖	3	31.00mil (0.787mm)	PTH	Slot	Top Layer — Bottom Layer	Pad
\Diamond	2	35.43mil (0.900mm)	PTH	Slot	Top Layer — Bottom Layer	Pad
×	43	38.00mil (0.965mm)	PTH	Round	Top Layer — Bottom Layer	Pad
A	4	40.00mil (1.016mm)	NPTH	Round	Top Layer — Bottom Layer	Pad
\bowtie	24	40.95mil (1.040mm)	PTH	Round	Top Layer — Bottom Layer	Pad
G	6	41.00mil (1.041mm)	NPTH	Round	Top Layer — Bottom Layer	Pad
D	12	41.00mil (1.041mm)	PTH	Round	Top Layer — Bottom Layer	Pad
©	15	43.00mil (1.092mm)	PTH	Round	Top Layer — Bottom Layer	Pad
0	5	50.00mil (1.270mm)	PTH	Round	Top Layer — Bottom Layer	Pad
×	2	61.02mil (1.550mm)	PTH	Round	Top Layer — Bottom Layer	Pad
Ε	2	62.00mil (1.575mm)	PTH	Round	Top Layer — Bottom Layer	Pad
¢	4	78.00mil (1.981mm)	PTH	Round	Top Layer — Bottom Layer	Pad
	4	120.00mil (3.048mm)	PTH	Round	Top Layer — Bottom Layer	Pad
F	2	130.00mil (3.302mm)	NPTH	Round	Top Layer — Bottom Layer	Pad
	2540 Total					
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Slot definitions: Routed Path Length = Calculated from tool start centre position to tool end centre position Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB la

LAYER STACK

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer	CF-003	1.40mil		
	Dielectric 1	370HR	8.00mil	4	
2	L2-GND	CF-004	0.70mil		
	Dielectric 2	370HR	8.00mil	4	
3	L3-SIG	CF-004	0.70mil		
	Dielectric 3	370HR	8.00mil	4	
4	L4-GND	CF-004	0.70mil		
	Dielectric 4	370HR	8.00mil	4	
5	L5-PWR	CF-004	0.70mil		
	Dielectric 5	370HR	8.00mil	4	
6	L6-SIG	CF-004	0.70mil		
	Dielectric 6	370HR	8.00mil	4	
7	L7-GND	CF-004	0.70mil		
	Dielectric 7	370HR	8.00mil	4	
8	Bottom Layer	CF-003	1.40mil		
	Bottom Solder	Solder Resist	O.40mil	3.5	
	Bottom Overlay				

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